

External_Type	Material_Group	Substances	CAS_Number	Mass	Mass_Percentage_in_Leaf	Massmg
Die	Doped Silicon	Silicon (Si)	7440-21-3	0.18	100.0	2.7
			<b>Subtotal</b>	<b>0.18</b>	<b>100</b>	<b>2.7</b>
Wire	Pure metal	Aluminium (Al)	7429-90-5	0.13	100.0	1.95
			<b>Subtotal</b>	<b>0.13</b>	<b>100</b>	<b>1.95</b>
Solder Wire	Tin alloy	Tin (Sn)	7440-31-5	0.03	5.0	0.5
	Silver alloy	Silver (Ag)	7440-22-4	0.01	1.5	0.15
	Lead alloy	Lead (Pb)	7439-92-1	0.62	93.5	9.35
			<b>Subtotal</b>	<b>0.66</b>	<b>100</b>	<b>10</b>
Lead Frame	Copper alloy	Phosphorous (P)	7723-14-0	0.01	0.03	0.15
	Pure metal layer	Zinc (Zn)	7440-66-6	0.01	0.02	0.1
	Pure metal layer	Tin (Sn)	7440-31-5	0.01	0.03	0.15
	Pure metal layer	Iron (Fe)	7439-89-6	0.04	0.11	0.54
	Pure metal layer	Copper (Cu)	7440-50-8	32.42	99.81	488.86
			<b>Subtotal</b>	<b>32.49</b>	<b>100</b>	<b>489.8</b>
Post-plating	Pure metal	Tin (Sn)	7440-31-5	0.34	100.0	5.17
			<b>Subtotal</b>	<b>0.34</b>	<b>100</b>	<b>5.17</b>
Mould Compound	Polymer	Phenol Formaldehyde resin (generic)	9003-35-4	3.31	5.0	49.92
	Polymer	Epichlorohydrin/Diethyleneglycol Epoxy resin (generic)	25928-94-3	9.93	15.0	149.77
	Filler	Silica fused	60676-86-0	2.98	4.5	44.93
	Carbon Black	Carbon black	1333-86-4	0.33	0.5	4.99
	Filler	Misc. Silica compounds (generic)	14808-60-7	49.66	75.0	748.83
			<b>Subtotal</b>	<b>66.21</b>	<b>100</b>	<b>998.44</b>
			<b>Total</b>	<b>100.01</b>	<b>100</b>	<b>1508.06</b>

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